



Material Content Data Sheet



Sales Product Name		IDP2303	Issued		25. January 2018			
MA#		MA001798476						
Package		PG-DSO-16-21	Weight*		175.55 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.504	3.14	3.14	31350	31350
leadframe	inorganic material	phosphorus	7723-14-0	0.023	0.01		129	
	non noble metal	zinc	7440-66-6	0.091	0.05		516	
	non noble metal	iron	7439-89-6	1.813	1.03		10325	
wire	non noble metal	copper	7440-50-8	73.601	41.92	43.01	419250	430220
	noble metal	palladium	7440-05-3	0.001	0.00		6	
	non noble metal	copper	7440-50-8	0.103	0.06	0.06	587	593
encapsulation	organic material	carbon black	1333-86-4	0.272	0.15		1547	
	plastics	epoxy resin	-	8.782	5.00		50024	
	inorganic material	silicondioxide	60676-86-0	81.481	46.42	51.57	464141	515712
leadfinish	non noble metal	tin	7440-31-5	1.562	0.89	0.89	8899	8899
plating	noble metal	silver	7440-22-4	0.641	0.37	0.37	3652	3652
glue	plastics	acrylic resin	-	0.370	0.21		2106	
	noble metal	silver	7440-22-4	1.311	0.75	0.96	7468	9574
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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